

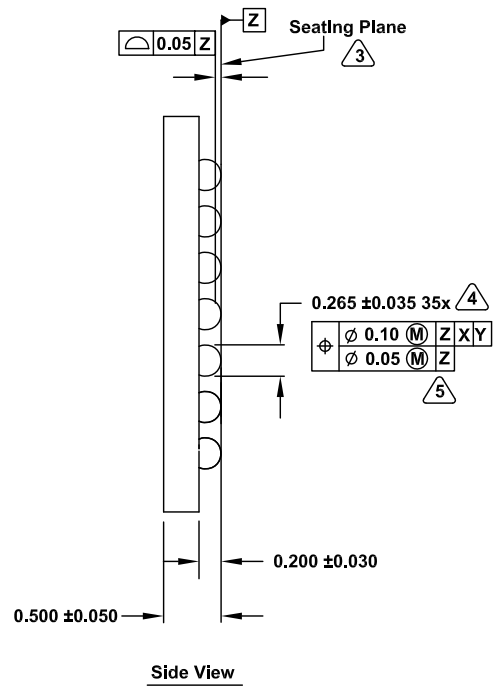
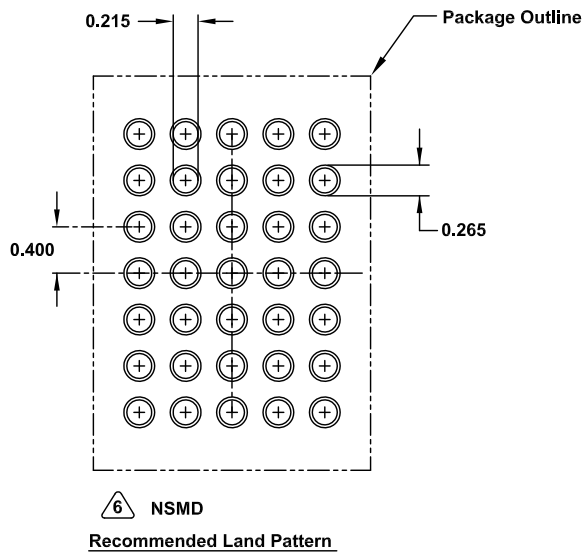
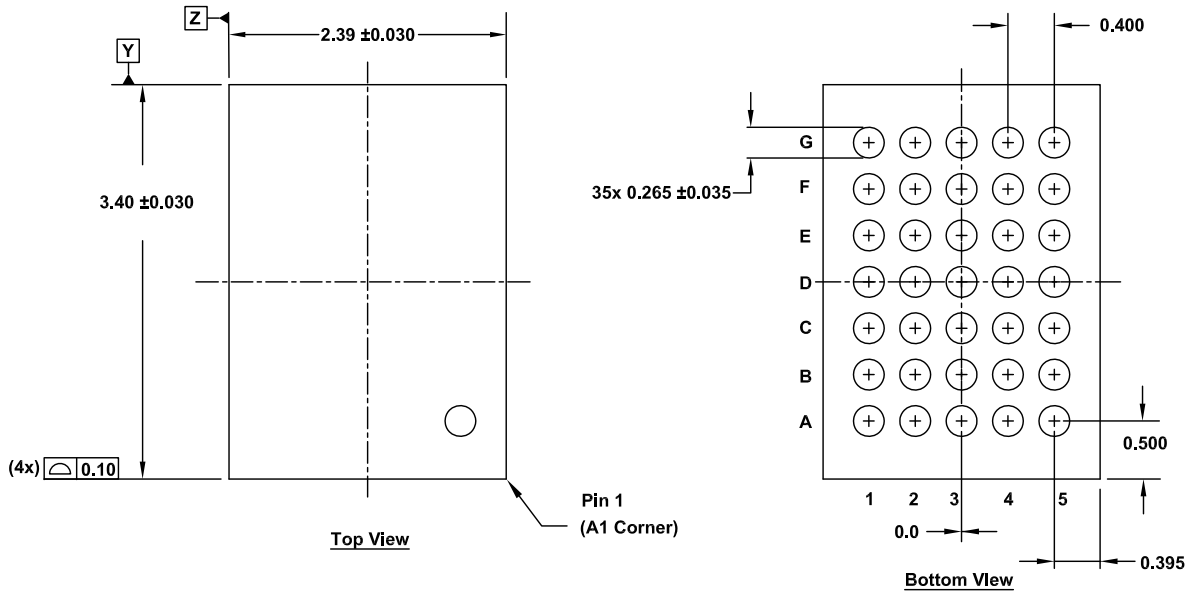
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

W5x7.35D

35 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)

Rev 1., 11/2021



### Notes:

1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASME Y14.5-1994.
3. Primary datum **Z** and seating plane are defined by the spherical crowns of the bump.
4. Dimension **Ls** is measured at the maximum bump diameter parallel to primary datum **Z**.
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per TB451.